

Automatic Cleaning System

A-CS-300

Stand-alone wafer cleaning unit, A-CS-300 provides best solution for cleaning and drying the wafer cut by semi-automatic dicing saws.

Air accelerated water nozzle and horizontal swing arm achieves excellent cleaning quality.

- Maximum rotation speed of spinning table: 3,000 min⁻¹
- Available frame size: 5" to 12" (Accretech standard frame type)
- Cleaning method: Air accelerated washing, Rinse,
Air dry (Driven by swing arm)
- Option: High pressure water cleaning



Specifications	
Frame size capability	Φ5" to Φ12" (Accretech standard frame type)
Spinning table speed	30 to 3000 min ⁻¹
Air accelerated washing	Pure water (0.3 MPa, 0.2 L/min) + Dry air (0.4 MPa, 100 L/min)
Rinse water pressure	Less than 0.4 MPa
Drying air pressure	Less than 0.7 MPa

Facilities	
Power supply	Three-phase AC 200V 50 to 60 Hz
Power consumption	3 kVA (Max.)
Air supply	0.5 to 0.7 MPa, 200 NL/min (ANR)
Water supply	0.2 to 0.5 MPa, 2 L/min
Dimension	490 ^W x 650 ^D x 1400 ^H mm
Over-all weight	160 kg

* When considering purchase, please contact our sales staff as the specification is subject to change without prior notice for improvement .

ACCRETECH

Japan / Head Office Tokyo Seimitsu Co., Ltd.
2968-2, Ishikawa-machi, Hachioji-shi, Tokyo, 192-8515 Japan
TEL : (042) 642-1701 FAX : (042) 642-1798
<https://www.accretech.com/en/>

● We reserve the right to change the contents of this catalog, including product specifications, without prior notice for improvements in products.

Contact
information

